1) USB Differential Pairs - 90 Ohm
   (A) USB-DM & USB-DP
   (B) USB0_GPIO-42 & USB0_GPIO-43
   (C) MCU_GPIO-42 & MCU_GPIO-43

2) EMIF - External Memory Interface Impedance Matching from J1 to U1
   (A) MCU_GPIO-39:41, MCU_GPIO-44:52, MCU_GPIO-86:94 - Address [0:21]
   (B) MCU_GPIO-85, MCU_GPIO-83:53 - Data [0:31]
   (C) MCU_GPIO-30 - Clock
   (D) MCU_GPIO-37, 31, 29 - Read/Write/ClkEn Pins
   (E) MCU_GPIO-32, 34, 35, 28 - Chip Select Pins

3) ADC Differential Pair Impedance Matching
   (A) HSEC_ADC even pins should match with HSEC_ADC + 1 pin (ie HSEC_ADC-C2 should match with HSEC_ADC-C3)
   (B) MCU_ADC even pins should match with MCU_ADC + 1 pin (ie MCU_ADC-A0 should match with MCU_ADC-A1)

   NOTES:

   1) USB Differential Pairs - 90 Ohm
      (A) USB-DM & USB-DP
      (B) USB0_GPIO-42 & USB0_GPIO-43
      (C) MCU_GPIO-42 & MCU_GPIO-43

   2) EMIF - External Memory Interface Impedance Matching from J1 to U1
      (A) MCU_GPIO-39:41, MCU_GPIO-44:52, MCU_GPIO-86:94 - Address [0:21]
      (B) MCU_GPIO-85, MCU_GPIO-83:53 - Data [0:31]
      (C) MCU_GPIO-30 - Clock
      (D) MCU_GPIO-37, 31, 29 - Read/Write/ClkEn Pins
      (E) MCU_GPIO-32, 34, 35, 28 - Chip Select Pins

   3) ADC Differential Pair Impedance Matching
      (A) HSEC_ADC even pins should match with HSEC_ADC + 1 pin (ie HSEC_ADC-C2 should match with HSEC_ADC-C3)
      (B) MCU_ADC even pins should match with MCU_ADC + 1 pin (ie MCU_ADC-A0 should match with MCU_ADC-A1)
1.1A Get Mode (Flash by default)
If desired, isolate (or semi-isolate) all GND nets on this page (GNDA) from the main GND. If done, the GND terminal of C82 should also go to GNDA.

All positions of SW2 should be in the ON/up state.
A:SW1 - Emulation & GPIO28 Switch
Pos 1 ON: Use xds100v2 emulator that is on the cCARD
Pos 1 OFF: Boot from FLASH/peripheral (see boot mode switch) OR use emulator on baseboard
Pos 2 ON: GPIO28 will be controlled by the USB-to-UART adapter on the FTDI chip
Pos 2 OFF: GPIO-28 can be controlled by a pin in HSEC connector
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